IN THE CLAIMS:

1.-14. (Canceled)

15. (Original) A method, comprising:

- commonly connecting source and drain regions of a plurality of transistor elements to a first electric potential by a first contact pad;
- commonly connecting gate electrodes of said plurality of transistor elements to a second electric potential by a second contact pad;
- connecting a common well region of said plurality of transistor elements to a third electric potential by a third contact pad; and
- assessing a reliability of gate insulation layers of said plurality of transistor elements by monitoring a gate leakage current of said plurality of transistor elements.

16. (Original) A method, comprising:

- N-channel transistor structure and at least one P-channel transistor structure to a first electric potential by a first contact pad;
- connecting a P-well region of said at least one N-channel transistor structure to a second electric potential by a second contact pad;
- connecting an N-well region of said at least one P-channel transistor structure to a third electric potential by a third contact pad; and

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assessing a reliability of gate insulation layers of said at least one N-channel transistor structure and said at least one P-channel transistor structure by determining a failure event.

- 17. (Original) The method of claim 16, wherein said second and third potentials are of opposite polarities.
- 18. (Original) The method of claim 17, wherein said second and third potentials are applied substantially simultaneously.
- 19. (Original) The method of claim 17, wherein said second and third potentials are applied sequentially.
- 20. (Original) The method of claim 19, wherein said second and third potentials are applied as pulses in an alternating manner.
- 21. (Original) The method of claim 16, wherein said failure event is determined by detecting abrupt changes of a signal indicative of a dielectric breakdown of a gate insulation layer of said at least one N-channel transistor structure and said at least one P-channel transistor structure.
- 22. (Original) The method of claim 21, wherein said signal represents a leakage current through said gate insulation layers.

23. (Canceled)